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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

2818

APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10067370	02/07/2002	438		2812	THAO SE

**APPLICANTS: Otsu Kazuhiro; Kobayashi Hideki; Sasaki Tatsuya; Ohya Kazuhiro;

**CONTINUING DATA VERIFIED:

** FOREIGN APPLICATIONS VERIFIED:

JAPAN 30746/01 02/07/2001

PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no		ATTORNEY DOCKET NO
35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no		2002-0208A
Verified and Acknowledged Examiners's initials		
TITLE : Separating machine for thinned semiconductor substrate and separation method		

U.S. DEPT. OF COMM./PAT. & TM.-PTO-436L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
Assistant Examiner		DRAWING	
		Sheets Drwg.	Figs. Drwg. Print Fig.
Primary Examiner		Application Examiner	
PREPARED FOR ISSUE			
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